



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :

Etsuko NAKAMURA et al. :

Serial No. 10/721,164 :

Attn: APPLICATION BRANCH

Filed November 26, 2003 :

Attorney Docket No. 2003_1698A

LOWER LAYER MATERIAL FOR
WIRING, EMBEDDED MATERIAL,
AND WIRING FORMATION METHOD :

Confirmation No. 5528

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In the interest of compact prosecution, please amend the present application as follows: